



In re Application of:

Chad A. Cobbley et al.

Serial No.:

10/771,085

Filed:

February 03, 2004

For:

STACKED DIE MODULE AND

TECHNIQUES FOR FORMING A

STACKED DIE MODULE

Group Art Unit:

2813

Examiner:

Blum, David S.

Atty Docket: MICS:0078-3/FLE/MANPOW

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Sir:

RESPONSE TO FINAL OFFICE ACTION MAILED AUGUST 30, 2005

In response to the Final Official Action mailed on August 30, 2005, Applicants presently amend the claims to place them in condition for allowance. Accordingly, Applicants respectfully request reconsideration of the above-identified application in view of the amendments and remarks set forth below.